

Product Change Notification / LIAL-12WRCV778

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19-Jan-2021

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 2927.001 and CCB 3280.002 Final Notice: Qualification of MTAI as an additional assembly and final test site for selected Atmel AT24C0xC, AT24C128C, AT24C16C, AT24C256C, AT24C32D and AT24C64D device families available in 8L SOIC package.

Affected CPNs:

LIAL-12WRCV778_Affected_CPN_01192021.pdf LIAL-12WRCV778_Affected_CPN_01192021.csv

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MTAI as an additional assembly and final test site for selected Atmel AT24C0xC, AT24C128C, AT24C16C, AT24C256C, AT24C32D and AT24C64D device families available in 8L SOIC package.

Pre Change:

Assembled at ANAP assembly site using palladium coated copper (PdCu) bond wire, 8290 die attach and G700A mold compound material with NiPdAu lead plating in 60 x 60 mils paddle size without lead lock.orAssembled at ASSH assembly site using palladium coated copper (PdCu) bond wire or palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900G die attach and G700LY molding compound or CEL-9240HF10AK mold compound material withNiPdAu or Matte tin lead plating in 93 x 93 mils paddle size without lead lock. and Tested at ASSH or ANAP Final Test site.

Post Change:Assembled at ANAP assembly site using palladium coated copper (PdCu) bond wire, 8290 die attach and G700A mold compound material with NiPdAu lead plating in 60 x 60 mils paddle size without lead lock**or**Assembled at ASSH assembly site using palladium coated copper (PdCu) bond wire or palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900G die attach and G700LY molding compound or CEL-9240HF10AK mold compound material withNiPdAu or Matte tin lead plating in 93 x 93 mils paddle size without lead lock.**Or**Assembled at MTAI assembly site using gold (Au) bond wire, 8390A die attach and G600V mold compound material with Matte tin lead plating in 90 x 90 mils paddle size with lead lock.**and**Tested at ASSH, ANAP or MTAI Final Test site.

Pre and Post Change Summary:

	Pro	e Change		Post Change					
Assembly Site	Amkor Technology Philippines (P1/P2), INC. (ANAP)	Semi (Shang	Advanced conductor hai) Co., Ltd. ASSH)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	s (P1/P2), Semiconductor (Shanghai) Co. Ltd.		Microchip Technology Thailand (HQ) (MTAI)		
Wire material	PdCu	PdCu	CuPdAu	PdCu	PdCu	CuPdAu	Au		
Die attach material	8290	EN	-4900G	8290	EN	I-4900G	8390A		
Molding compound material	G700A	G700LY	CEL-9240HF 10AK	G700A	G700LY	CEL-9240HF 10AK	G600V		
Lead frame material	CDA194	С	DA194	CDA194 CDA19		DA194	CDA194		
Paddle size	60 x 60 mils	93 :	x 93 mils	60 x 60 mils 93 x 93 mils		x 93 mils	90 x 90 mils		
Lead Lock	No		No	No	No		Yes		
Lead Plating	NiPdAu	NiPdAu	Matte tin	NiPdAu	NiPdAu Matte tin		Matte Tin		

		Pre Cl	nange	Post Change				
Final Test Site		ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	Microchip Technology Thailand (MTAI)		
Base Quantity	Tube	100	100	100	100	100		
Multiple (BQM)	Tape and Reel	4000	4000 4000 4000		4000	4000		
Pin1	Tube	Pin 1 side (Black)	Not Applicable	Pin 1 side (Black)	Not Applicable	Pin 1 side (White)		
Orientation	Tape and Reel	Quadrant 1	Quadrant 1	Quadrant 1	Quadrant 1	Quadrant 1		

Tube	Minor dimensional changes – see attachment
Carrier Tape	No change
Cover Tape	Minor dimensional changes – see attachment
Plastic Reel	Minor dimensional changes – see attachment
Packing Procedure for Tube and Tape & Reel	See attachment

Impacts to Data Sheet:None

Change Impact: None

Reason for Change:To improve on-time delivery performance by qualifying MTAI as an additional assembly and final test site

Change Implementation Status:In Progress

Estimated First Ship Date: February 15, 2021 (date code: 2108)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	January 2021				Feb	ruary	2021			
Workweek	01	02	03	04	05	06	07	08	09	10
Qual Report Availability				Х						
Final PCN Issue Date		х								
Estimated First Ship Date							Х			

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.PCN_ LIAL-12WRCV778 Qual_Report – Assembly site Qualification ReportPCN_ LIAL-12WRCV778_Qual_Report – Final Test site Qualification Report

Revision History:January 19, 2021: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 15, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-12WRCV778_Pre and Post Change Summary.pdf PCN LIAL-12WRCV778_ Qual Report - Assembly.pdf PCN LIAL-12WRCV778_ Qual Report - Final Test.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected part numbers

AT24C04C-SSHM-B

AT24C04C-SSHM-T

AT24C08C-SSHM-B

AT24C08C-SSHM-T

AT24C01C-SSHM-B

AT24C01C-SSHM-T

AT24C02C-SSHM-B

AT24C02C-SSHM-T

AT24C256C-SSHL-B

AT24C256C-SSHL-T

AT24C16C-SSHM-B

AT24C16C-SSHM-T

AT24C64D-SSHM-B

AT24C64D-SSHM-T

AT24C128C-SSHM-B

AT24C128C-SSHM-T

AT24C32D-SSHM-B

AT24C32D-SSHM-T



QUALIFICATION REPORT SUMMARY RELIABILITY LABORATORY

PCN#: LIAL-12WRCV778

Date June 24, 2017

Qualification of MTAI as an additional assembly site for selected Atmel AT24C0xC, AT24C128C, AT24C16C, AT24C256C, AT24C32D and AT24C64D device families available in 8L SOIC package.



Purpose Qualification of MTAI as an additional assembly site for selected Atmel AT24C0xC,

AT24C128C, AT24C16C, AT24C256C, AT24C32D and AT24C64D device families

available in 8L SOIC package.

CN ES098794

QUAL ID Q17084 Rev A

CCB 2927.001

 MP CODE
 DEDX2YC2XA00

 Part No.
 24LC512T-E/SN

Bonding No. BDM-001302 Rev. A

Package

Type 8L SOIC Package size 150 mils

Lead Frame

Paddle size 95 x 130 mils

Material CDA194

Surface Bare Cu paddle

Process Stamped

Lead Lock Yes

Part Number 10100842
Treatment Roughened

<u>Material</u>

Epoxy 8390A Wire Au

Mold Compound G600V
Plating Composition Matte Tin



Manufacturing Information

Assembly Lot No.	Wafer No.	Date Code
MTAI180702622.000	GRSM417152115.300	1719PE7
MTAI180702623.000	GRSM417152115.340	1719PE8
MTAI180703101.000	GRSM417152115.300	1719U5E

Result	X Pass	Fail	
rtocart	11 1 400	a	

8L SOIC (.150") assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

	PACKAGE QUALIFICATION REPORT										
Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks					
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020D)	IPC/JEDE C J-STD- 020D	135	0/135	Pass						

Precondition Prior Perform	Electrical Test :+25°C,85°C and 125°C System: NEXTEST_PT	JESD22- A113	693(0)	693		Good Devices
Reliability Tests (At MSL Level 1)	Bake 150°C, 24 hrs System: CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max			693		
	System: Vitronics Soltec MR1243					
	Electrical Test :+25°C,85°C and 125°C System: NEXTEST_PT			0/693	Pass	

	PACKAGE QUALIFICA	ATION	REF	ORT		
Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
	Stress Condition: -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H	JESD22- A104		231		Parts had been pre-conditioned at 260°C
Temp Cycle	Electrical Test: + 85°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (> 2.5 grams)		15 (0)	0/15	Pass	
	Bond Shear (>15.00 grams)		15 (0)	0/15	Pass	
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22- A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X	JESD22- A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test:+25°C,85°C and 125°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs System: SHEL LAB	JESD22- A103		45		45 units
•	Electrical Test :+25°C,85°C and 125°C System: NEXTEST_PT		45(0)	0/45	Pass	

	PACKAGE QUALIFIC	ATION	IREF	PORT	•	
Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Solderability Temp 215°C	Steam Aging: Temp 93°C,8Hrs System: SAS-3000 Solder Dipping: Solder Temp.215°C Solder material: SnPb Sn63,Pb37 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	JESD22B- 102E	22 (0)	22 22 0/22	Pass	
Solderability Temp 245°C	Steam Aging: Temp 93°C,8Hrs System: SAS-3000 Solder Dipping:Solder Temp.245°C Solder material:Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	JESD22B- 102E	22 (0)	22 22 0/22	Pass	
Bond Strength Data Assembly	Wire Pull (> 2.5 grams) Bond Shear (>15.00 grams)	M2011 JESD22- B116	30 (0) Wires 30 (0) bonds	0/30	Pass	

CCB 2927.001 and 3280.002 Pre and Post Change Summary PCN #: LIAL-12WRCV778



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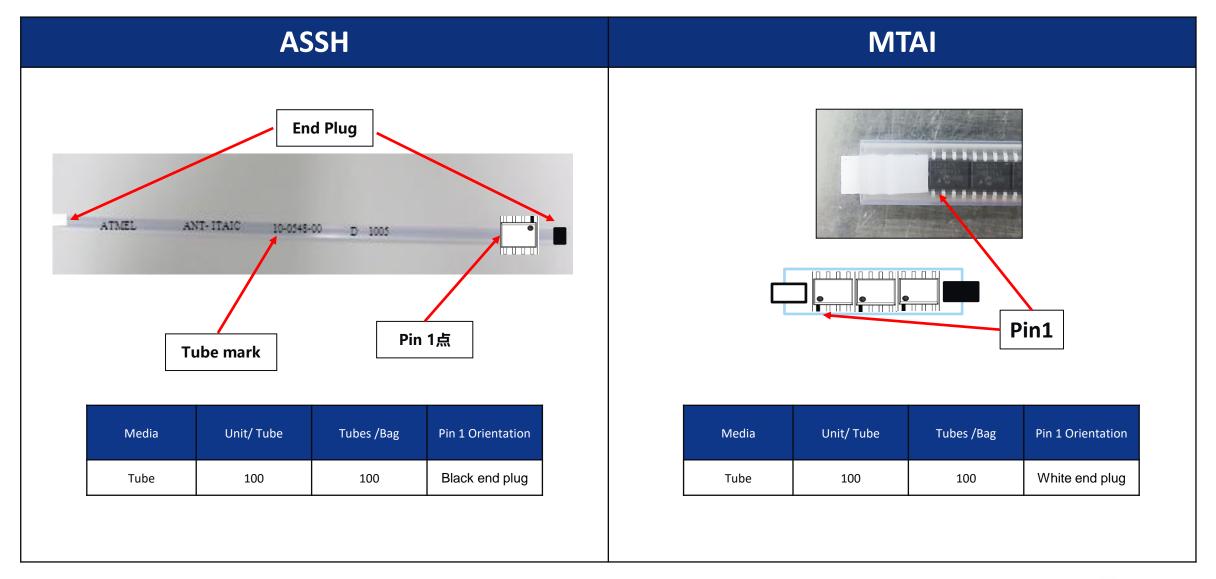
Qualification of MTAI as an additional assembly and final test site for selected Atmel for selected Atmel AT24C0xC, AT24C128C, AT24C16C, AT24C256C, AT24C32D and AT24C64D device families available in 8L SOIC package.

LEAD FRAME COMPARISON

AN	AP	AS	SH	N	ITAI
	2 4	8 7	6 5	Lead Lock	6 5
Paddle size	60 x 60 mils	Paddle size	93 x 93 mils	Paddle size	90 x 90 mils
Lead Lock	No	Lead Lock	No	Lead Lock	Yes
Lead Plating	NiPdAu	Lead Plating	Matte tin	Lead Plating	Matte Tin

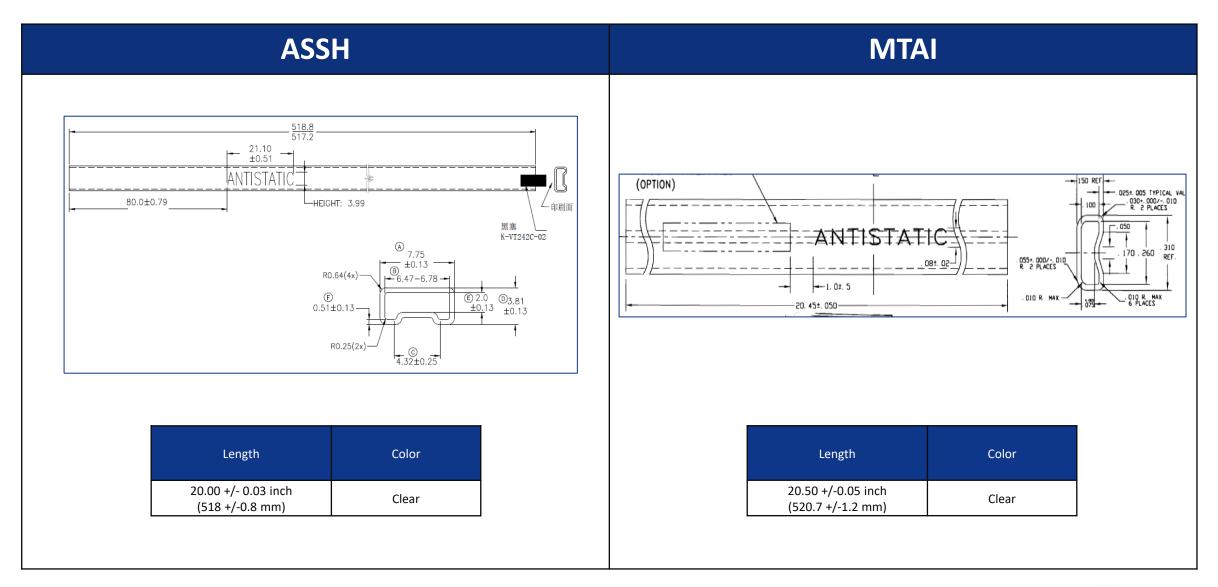


TUBE BQM AND PIN1 ORIENTATION



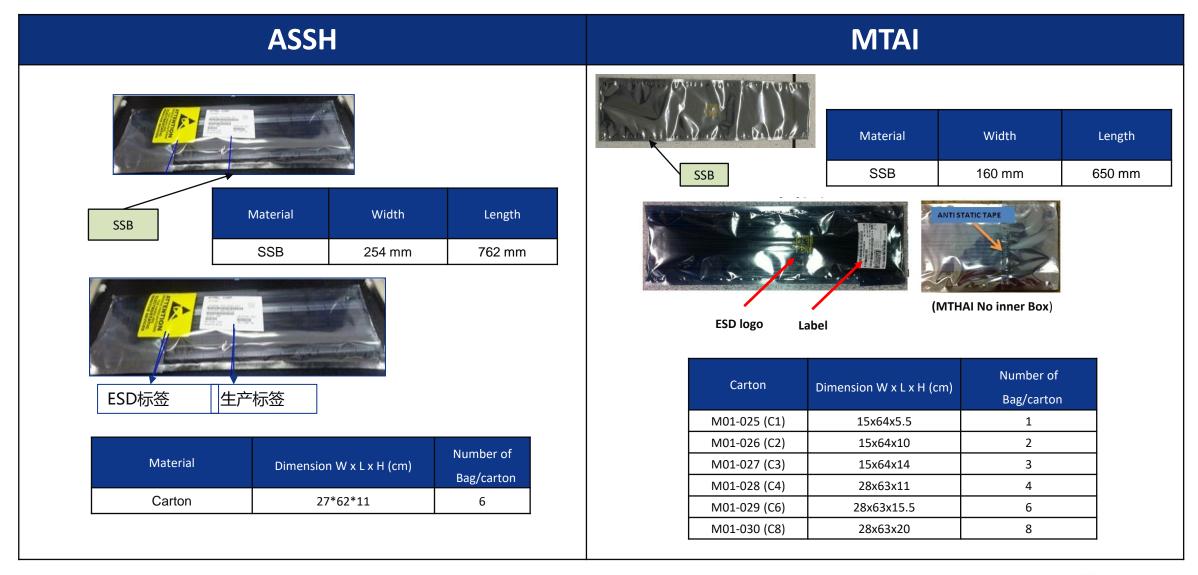


TUBE DIMENSION – Minor changes



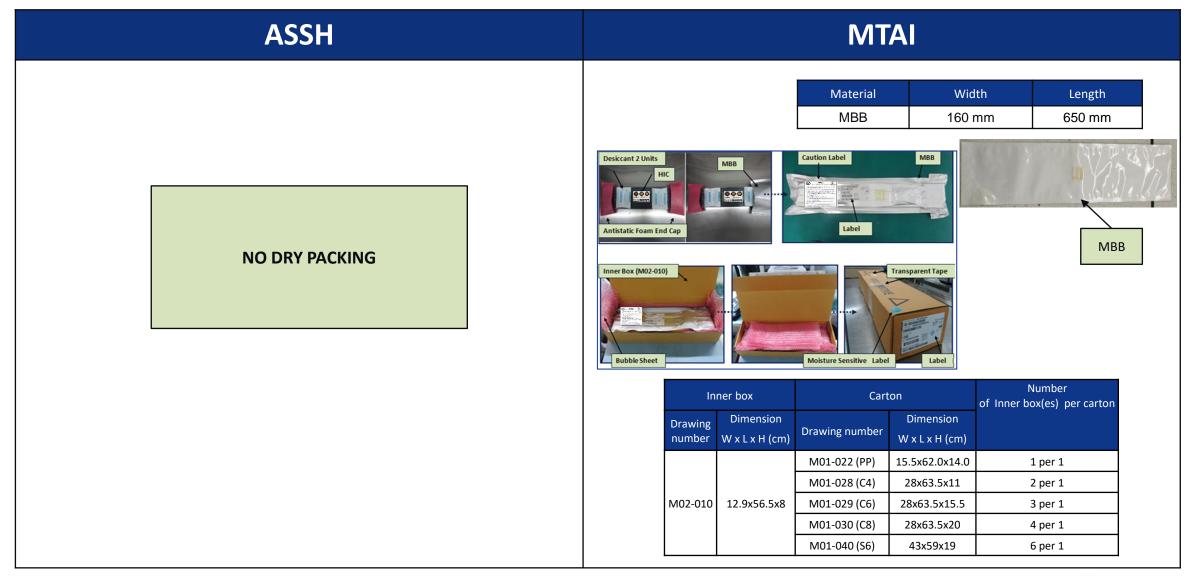


TUBE NON-DRY PACK



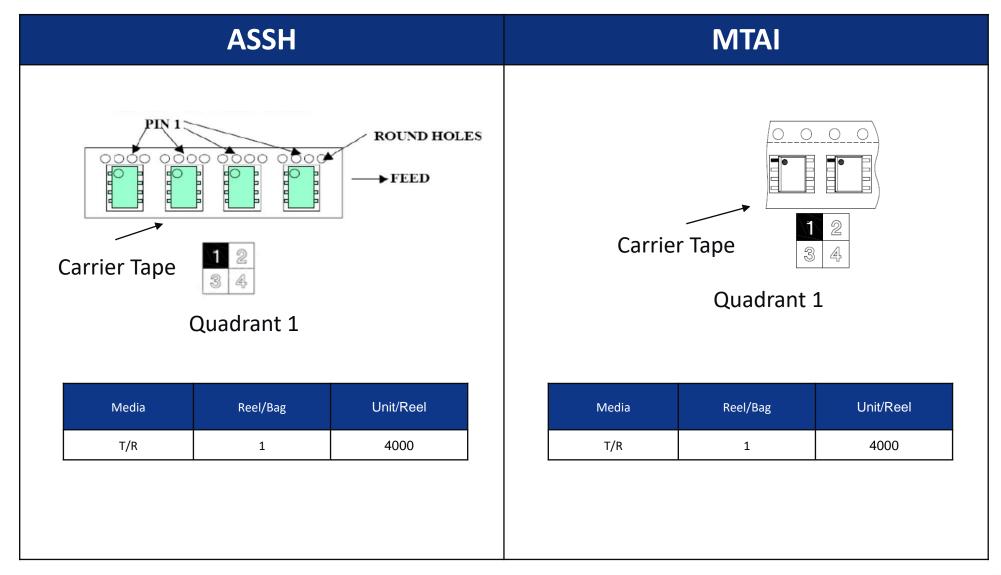


TUBE DRY PACK



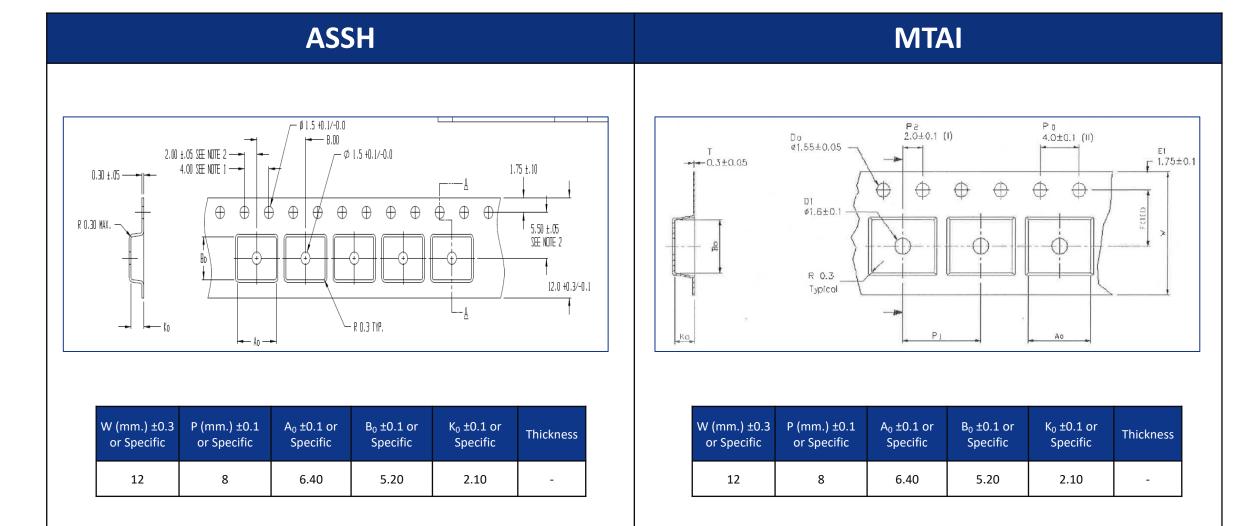


T/R BQM AND PIN1 ORIENTATION



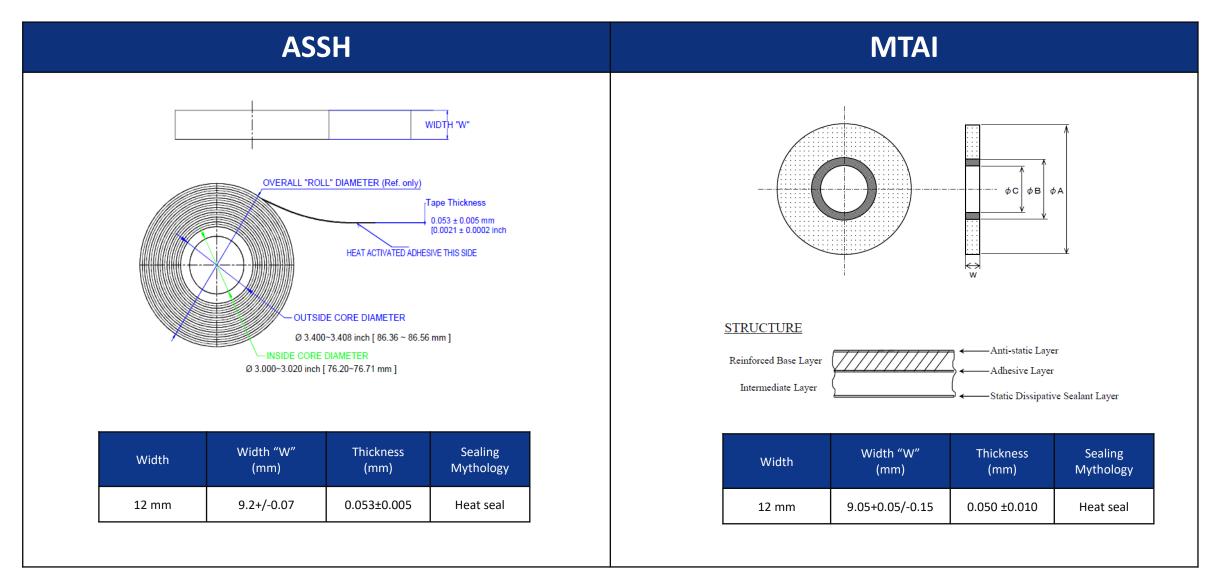


CARRIER TAPE – No changes



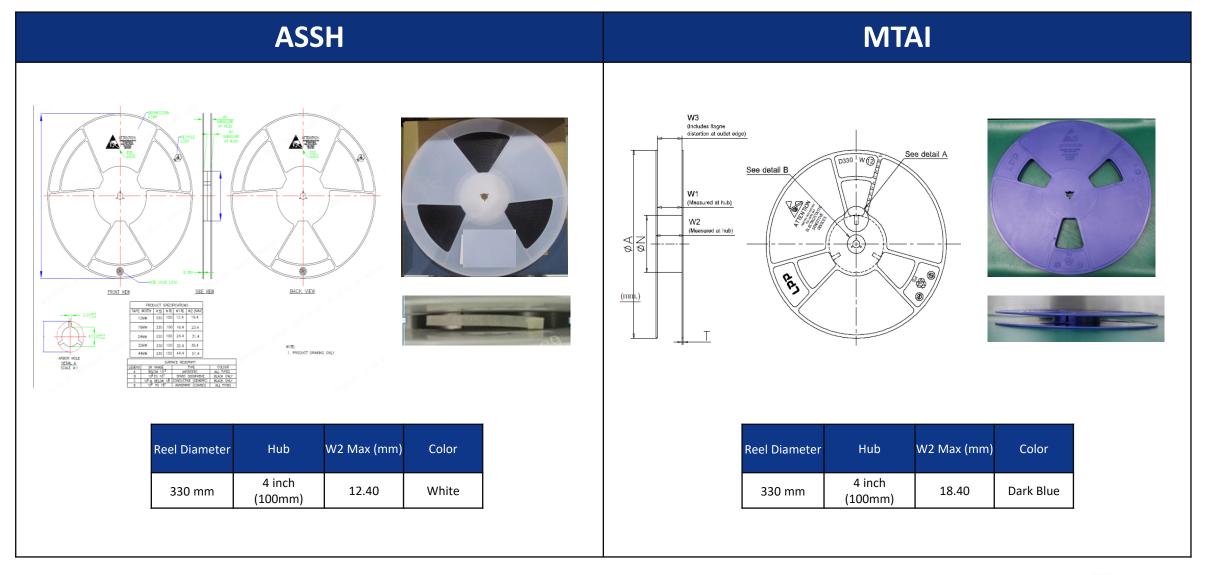


COVER TAPE – Minor changes



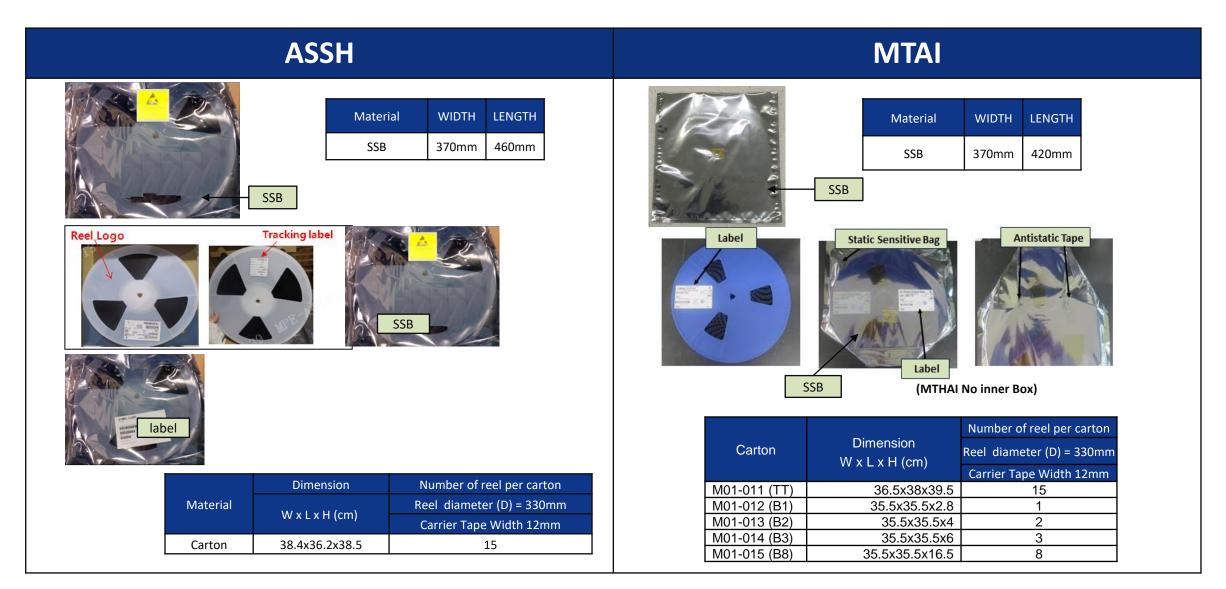


PLASTIC REEL – Minor changes



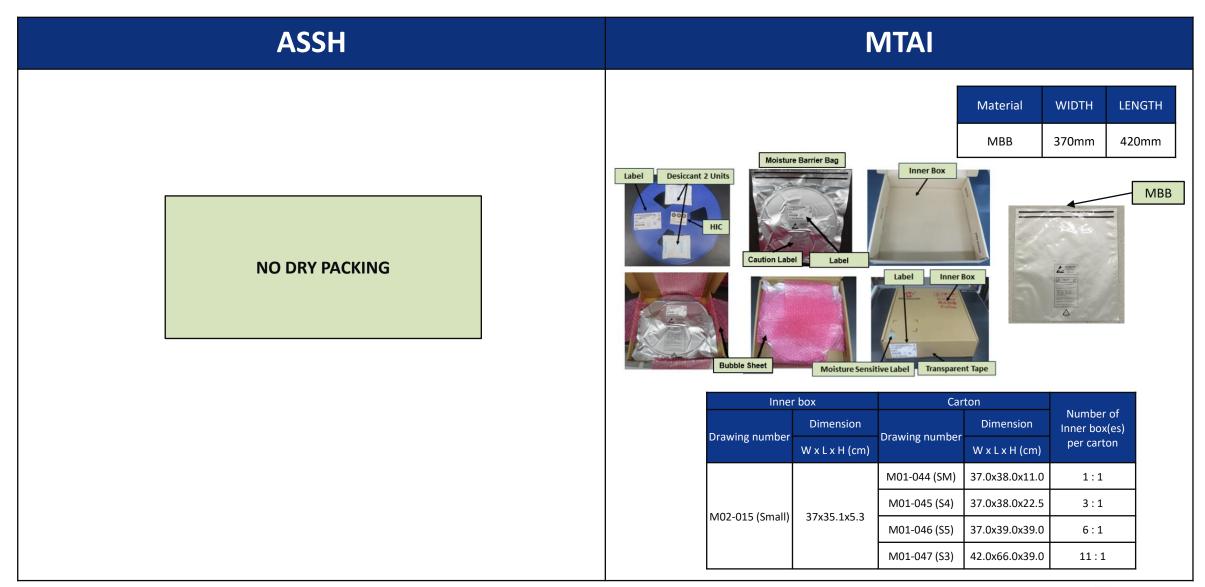


T/R NON-DRY PACK



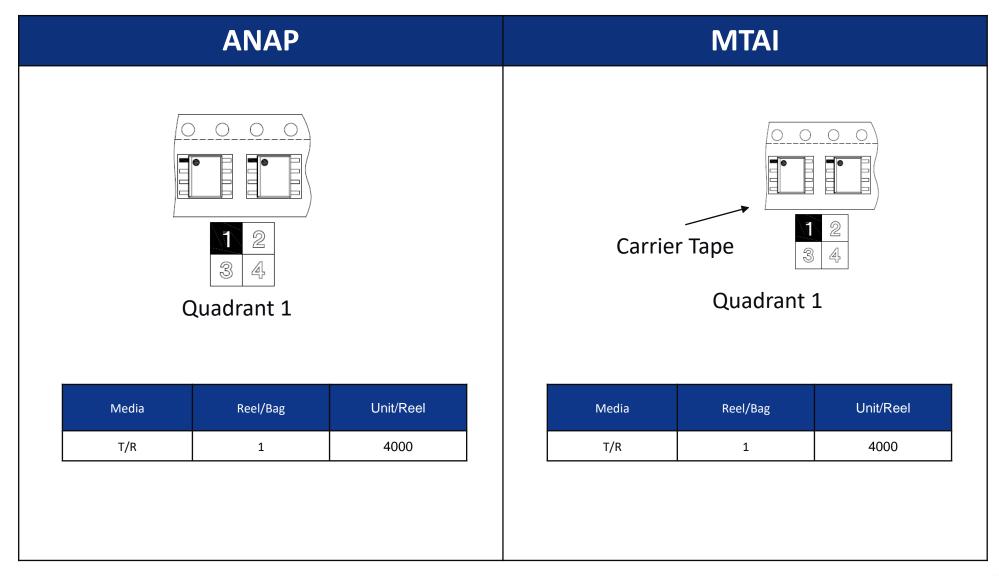


T/R DRY PACK



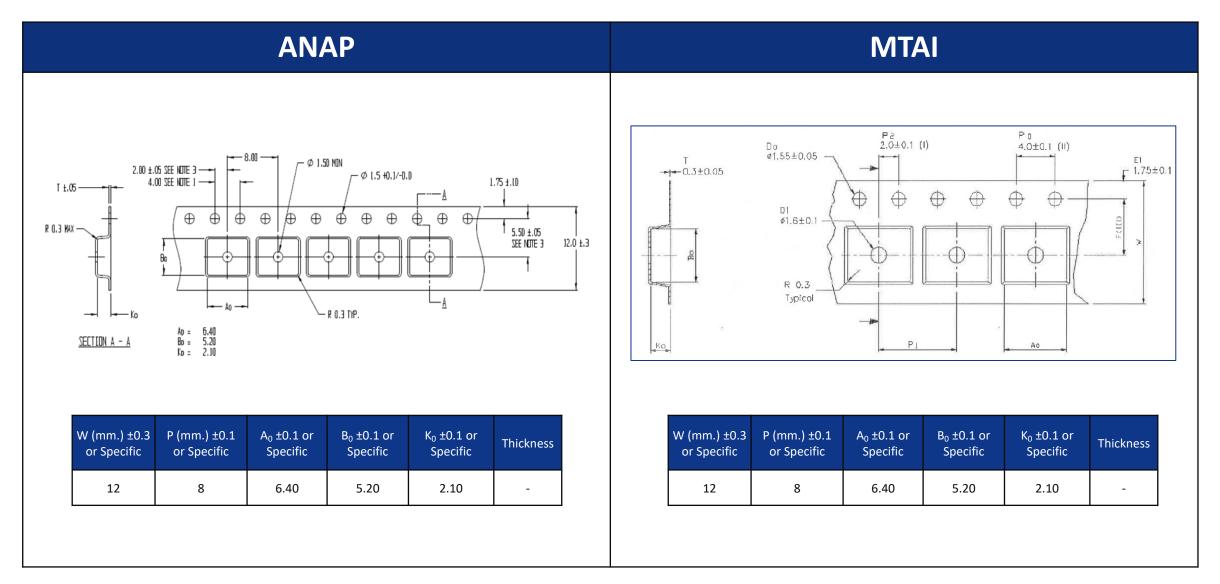


T/R BQM AND PIN1 ORIENTATION



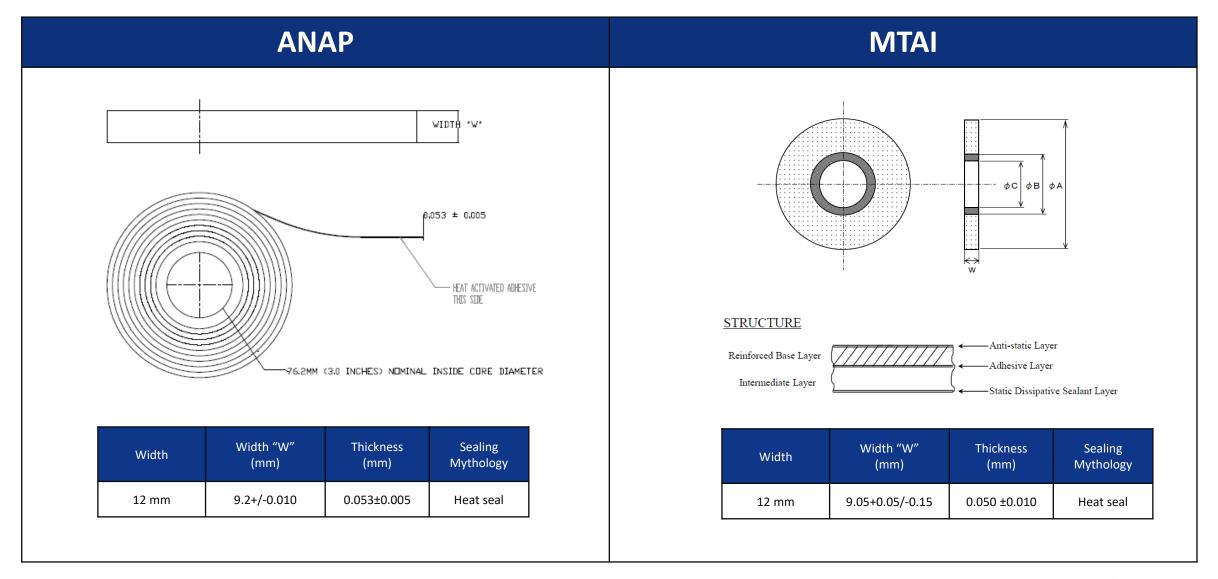


CARRIER TAPE – No changes



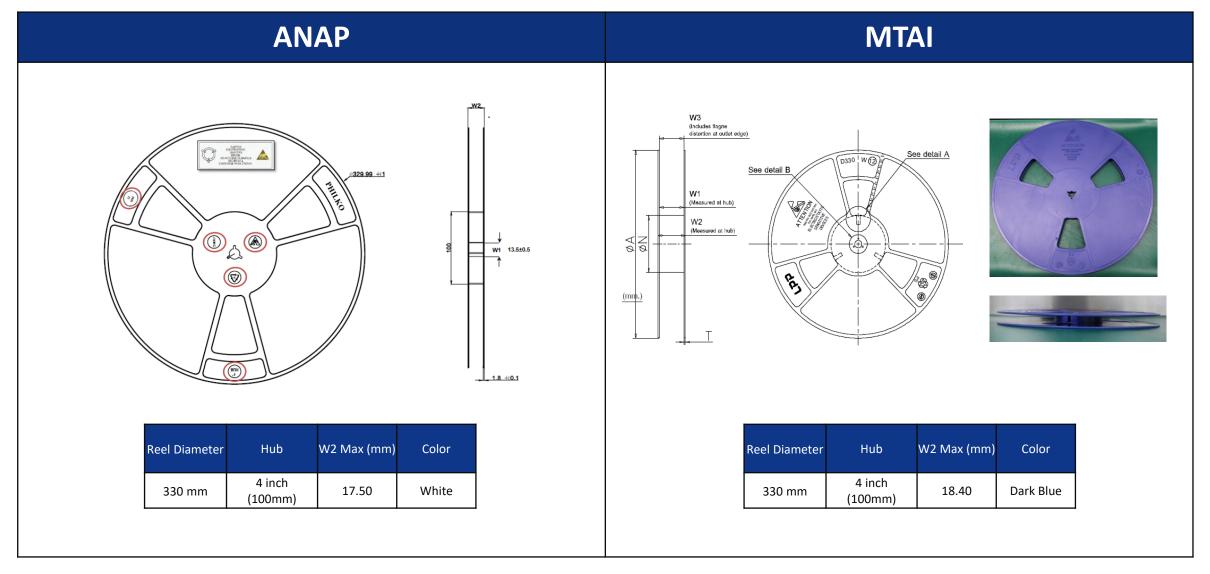


COVER TAPE – Minor changes



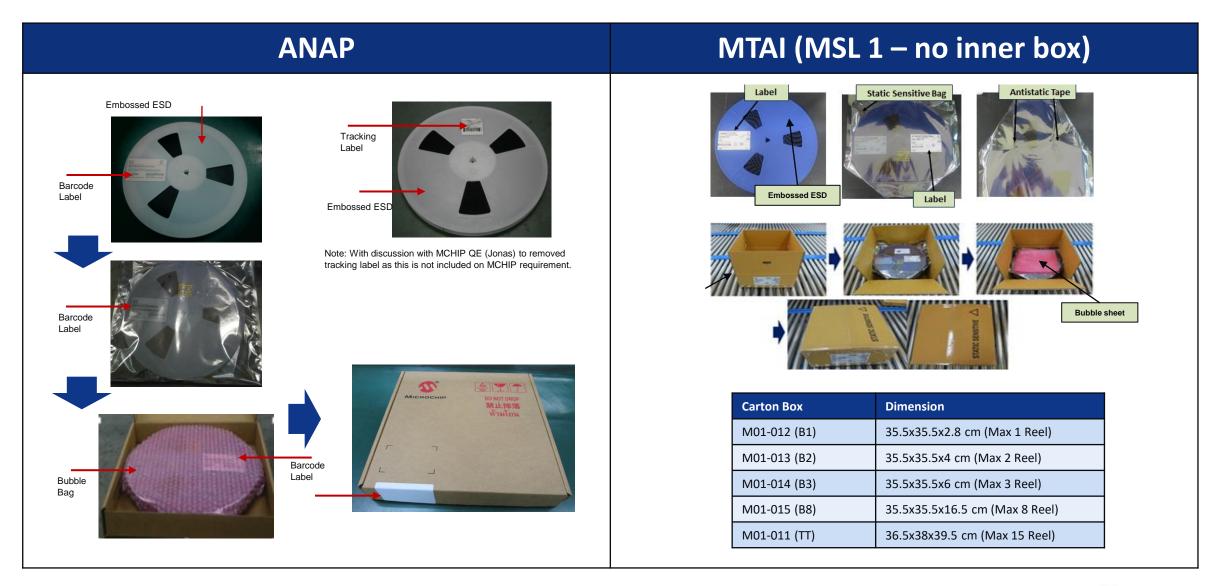


PLASTIC REEL – Minor changes





T/R NON-DRY PACK







QUALIFICATION REPORT SUMMARY

PCN #: LIAL-12WRCV778

Date: December 08, 2020

Qualification of MTAI as an additional final test site for selected Atmel AT24C0xC, AT24C128C, AT24C16C, AT24C256C, AT24C32D and AT24C64D device families available in 8L SOIC package.

Purpose: Qualification of MTAI as a additional final test site for selected Atmel

AT24C0xC, AT24C128C, AT24C16C, AT24C256C, AT24C32D and

AT24C64D device families available in 8L SOIC package.

CCB No.: 3280.002

Test / Evaluation	Test Conditions / Parameters	Results / Remarks
Datalog / Bin Comparison	 Compare test numbers, test names, test limit, test sequence, bin assignments & pass/fail results. Accept if all match or justify the differences 	PASSED
Test stability verification	 Test stability verification with TC at -40°C, 25°C and 85°C for singulated Accept on Cpk > 1.67 or justify/waive parameters if needed 	PASSED
Tester to Tester verification	Perform GR&R. Site 1: Nextest_PT vs Nextest_SSV2t Platform	PASSED
Yield correlation	 Lot Validation, Good vs. rejects comparison. (5000 pcs). Accept ± 2% yield difference 	PASSED
Rejects verification	The one failure is marginal fail at 85C with Singulates test program, but on Strip test program the failure get always pass result. Reject rate is 0%.	PASSED